






APPLICABLE STANDARD							
RATING	OPERATING TEMPERATURE RANGE	-40°C TO + 85°C (NOTE 1) 		STORAGE TEMPERATURE RANGE		-10°C TO + 60°C (NOTE 2)	
	OPERATING HUMIDITY RANGE	40% TO 80% (NOTE 3)		STORAGE HUMIDITY RANGE		40% TO 70% (NOTE 2)	
	VOLTAGE	AC 250V		UL·CSA	VOLTAGE	AC 30V	
	CURRENT	2A		RATING	CURRENT	2A	
SPECIFICATIONS							
ITEM		TEST METHOD		REQUIREMENTS		QT	AT
CONSTRUCTION							
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.		X	X
MARKING		CONFIRMED VISUALLY.				X	X
ELECTRIC CHARACTERISTICS							
CONTACT RESISTANCE		100mA (DC OR 1000 Hz).		30mΩ MAX.		X	—
INSULATION RESISTANCE		500V DC.		1000MΩ MIN.		X	—
VOLTAGE PROOF		650V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.		X	—
MECHANICAL CHARACTERISTICS							
MECHANICAL OPERATION		30TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 30mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
ENVIRONMENTAL CHARACTERISTICS							
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.		① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55→ 5 TO 35→+85→ 5 TO 35°C TIME 30→ 5MAX → 30→ 5MAX min UNDER 5 CYCLES.		① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 1000MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
RESISTANCE TO SOLDERING HEAT		1)AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE : 260°C FOR IMMERSION,DURATION , 10 sec . 2)MANUAL SOLDERING SOLDERING IRON TEMPERATURE : 300°C SOLDERING TIME : 2 sec. NO STRENGTH ON CONTACT.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.		x	—
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE, 230°C FOR INSERTION DURATION, 3sec.		SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.		X	—
	COUNT	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE	
	1	DIS-H-008540		MI. SAKIMURA	HK. UMEHARA	14. 02. 26	
REMARKS NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. NOTE3:NON-CONDENSING. Unless otherwise specified , refer to IEC 60512.					APPROVED	TY. OMA	05. 08. 11
					CHECKED	HK. UMEHARA	05. 08. 11
					DESIGNED	IO. DENPOUYA	05. 08. 11
					DRAWN	MK. MATSUO	05. 08. 09
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				DRAWING NO.		ELC4-162391-02	
	SPECIFICATION SHEET			PART NO.	DF11-*DP-2DSA (24)		
	HIROSE ELECTRIC CO., LTD.			CODE NO.	CL543  1/ 1		